

Notice of References Cited			Application No. 08/856,116	Applicant(s) Chen et al.		
			Examiner Bernard Souw	Group Art Unit 2814	Page 1 of 1	
U.S. PATENT DOCUMENTS						
	DOCUMENT NO.	DATE	NAME		CLASS	SUBCLASS
A	5,308,793	05/03/94	Taguchi et al.		437	194
B	5,178,739	01/12/93	Barnes E T Al.		204	192.12
C	5,354,712	10/11/94	Ho et al.		437	195
D	5,486,492	01/23/96	Yamamoto et al.		437	192
E						
F						
G						
H						
I						
J						
K						
L						
M						
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
N						
O						
P						
Q						
R						
S						
T						
NON-PATENT DOCUMENTS						
	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)					DATE
u	R.F. Bunshah, "Handbook of Deposition Technologies for Films and Coatings", 2nd edition, Noyes Publications, NJ, USA, 1994, p..261					1994
v	Gardner et al., "Encapsulated Copper Interconnection Device using Sidewall Barriers", Thin Solid Films 262 (1995) 104-119					1995
w	Jang et al., "Tantalum and Niobium as a Diffusion Barrier between Copper and Silicon", J. Materials Science: Materials in Electronics 7 (1996) 271-278					1996
x						